Floorguard Products

06

TECHNICAL REFERENCE SHEET
DEW POINT OVERVIEW

DETERMINING DEW POINT & CONDENSATION RISK DURING INSTALLATIONS

OVERVIEW

Dew point is the temperature at which moisture in the air condenses on surfaces. If a substrate is at or below dew point, condensation will occur, leading to adhesion failure, amine blush, improper cure, or surface hazing. Dew point verification is mandatory for all resinous flooring installations.

How to Calculate Dew Point

Use a digital psychrometer or dew point chart below. Dew point is determined by:

- Ambient temperature
- Relative humidity

Dew Point Rule:

- Substrate must be at least 5°F (3°C) above dew point during installation and cure.

Why Dew Point Matters

- Condensation forms microscopic water film invisible to the eye.
- Coatings applied over condensation will fail.
- High humidity reduces allowable temperature ranges.

Installer Checklist

- Verify dew point before mixing materials.
- Continuously monitor throughout installation.
- Avoid coating during rapid temperature drops (evening).
- Use indirect heat/dehumidification when required.

Dew Point Chart:

	RELATIVE HUMIDITY %						
AIR TEMP °F	30%	40%	50%	60%	70%	80%	90%
40°F	12°F	17°F	22°F	26°F	30°F	33°F	36°F
50°F	24°F	30°F	36°F	41°F	45°F	48°F	50°F
60°F	35°F	41°F	48°F	53°F	57°F	59°F	61°F
70°F	46°F	52°F	59°F	64°F	68°F	69°F	70°F
80°F	57°F	63°F	68°F	73°F	76°F	78°F	79°F
90°F	68°F	73°F	77°F	81°F	84°F	86°F	88°F
100°F	79°F	83°F	86°F	90°F	92°F	94°F	96°F